

Preliminary Amendment submitted in  
response to Notice of Non-Compliant  
Amendment mailed 11/01/2004  
U.S. Pat App. No. 10/826,211  
Page 3  
November 18, 2004

**Amendments to the Claims:**

Please make the following amendments to the claims, which are presented here in their entirety from the parent application:

Claims 1 – 19            Cancelled

Claim 20 (Original)    An interconnect structure, comprising:

    a low-k dielectric without an intermediate etch-stop layer;

    a trench having a plurality of trench edges, said plurality of trench edges having a substantially orthogonal shape, said trench having a first width and a first depth within said low-k dielectric;

    a via beneath said trench and within said low-k dielectric, said via having a plurality of via edges, said plurality of via edges having a substantially orthogonal shape, said via having a second width and a second depth, said second width being smaller than said trench first width and second depth being greater than said trench first depth.

Claim 21 (Original)    The interconnect structure of claim 20 further comprising a terrace between said trench and said via, said terrace having a third width that is greater than said second via width.

Claim 22 (Original)    The interconnect structure of claim 20 further comprising a metallized object beneath said via.

Claim 23 (Original)    The interconnect structure of claim 21 further comprising a metallized object beneath said via.

Claim 24 (Original)    The interconnect structure of claim 20 wherein said interconnect structure is a dual damascene structure.